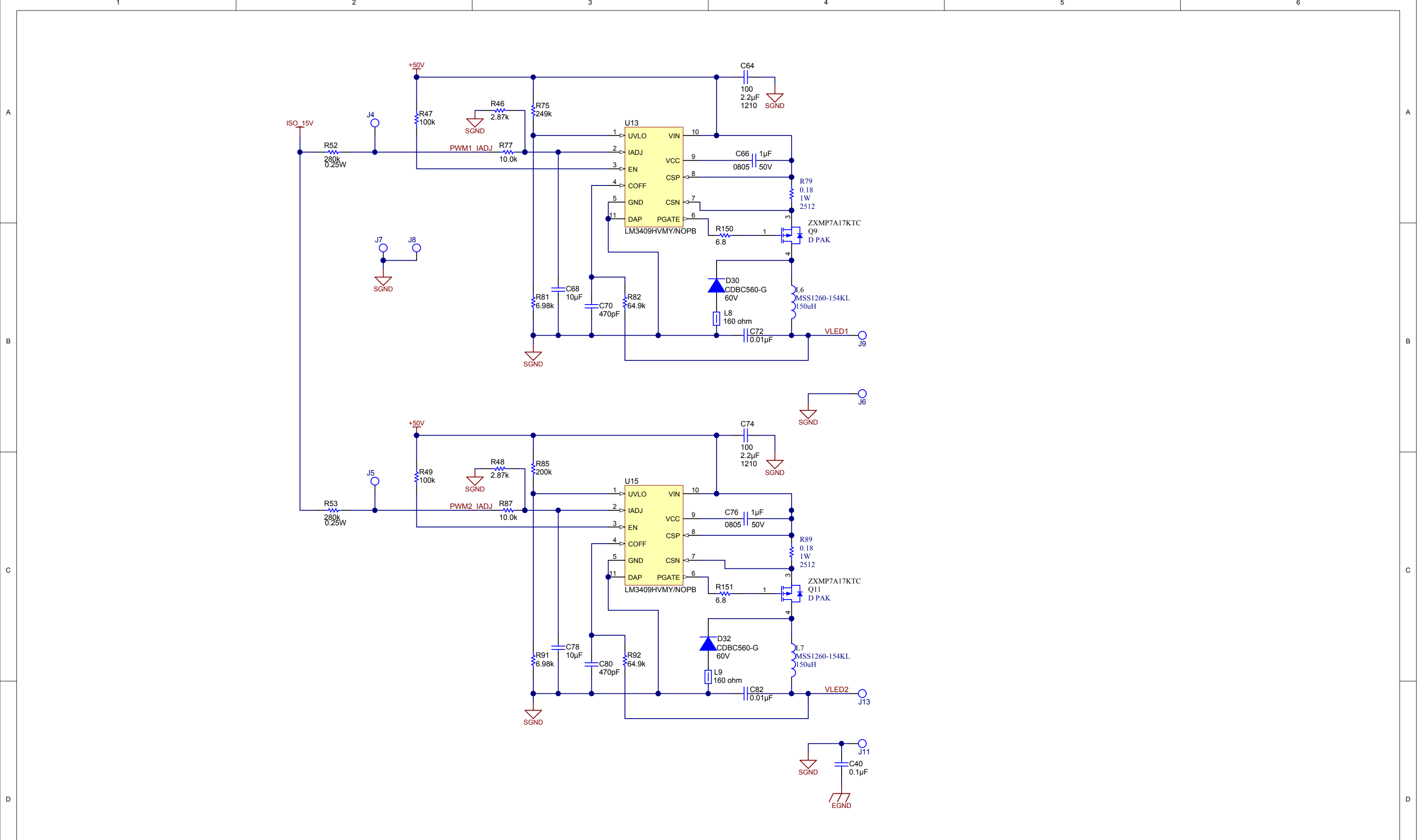



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Designed for:		Mod. Date: 8/14/2014	
Project Title: Fly Buck		Sheet Title: UC28810 Flyback PFC Primary Stage	
Number: PMP6024	Rev: A	Assembly Variant: 001	Sheet: 1 of 3
SVN Rev: Not in version control	Drawn By: Monty Doshi	File: PMP6024A_pg1.SchDoc	Size: B
Engineer: David Zhang	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>		© Texas Instruments 2014



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Number: PMP6024	Rev: A	Designed for:	Mod. Date: 8/14/2014
SVN Rev: Not in version control	Sheet: 2 of 3	Project Title: Fly Buck	
Drawn By: Montu Doshi	File: PMP6024A_pg2.SchDoc	Sheet Title: FlyBack2	
Engineer: David Zhang	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	Assembly Variant: 001	Size: B


  
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FID1



FID4

PCB Number: PMP6024  
PCB Rev: A

PCB  
LOGO  
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FID2



FID3

ZZ2  
Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

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Designed for:		Mod. Date: 8/14/2014	
Project Title: Fly Buck			
Sheet Title: Hardware			
Number: PMP6024	Rev: A	Assembly Variant: 001	Sheet: 3 of 3
SVN Rev: Not in version control	Drawn By: Montu Doshi	File: PMP6024A_Hardware.SchDoc	Size: B
Engineer: David Zhang	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>		



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